

BF 2012 Series

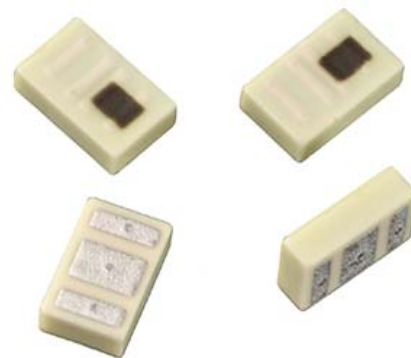
Multilayer Chip Band-Pass Filters

Features

- ❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.
- ❖ RoHS compliant.

Applications

- ❖ Wireless communication systems.



Specifications

Part Number	Frequency Range (MHz)	Insertion Loss @ BW (dB)	Return Loss @ BW (dB)	Frequency	Attenuation (dB)
BF2012-R3R8NAA_	3300~ 4200	1.2 typ. / 1.4 max.	10 min.	DC ~ 2170MHz	40 min.
				2300 ~ 2700MHz	30 min.
				5500 ~ 5850MHz	20 min.

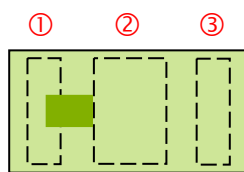
Q'ty/Reel (pcs)	: 4,000
Operating Temperature Range	: -40 ~ +85 °C
Storage Temperature Range	: -40 ~ +85 °C
Storage Period	: 12 months max.
Power Capacity	: 3W max.
MSL	: Level 1
ESD HBM	: ±2000V

Part Number

BF 2012 - R 3R8 NAA □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	BF : Band-Pass Filter	② Dimensions (L × W)	2.0 × 1.25 mm
③ Material Code	R	④ Frequency Range	3R8=3800MHz
⑤ Specification Code	NAA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

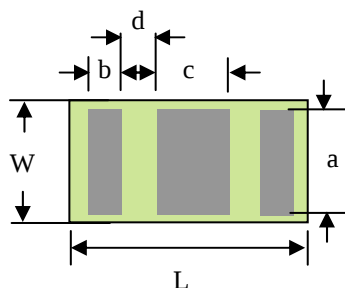
Terminal Configuration



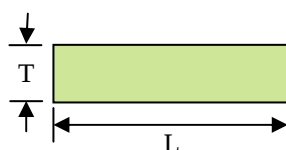
No.	Terminal Name	No.	Terminal Name
①	IN	③	OUT
②	GND		

Dimensions and Recommended PC Board Pattern

Unit : mm

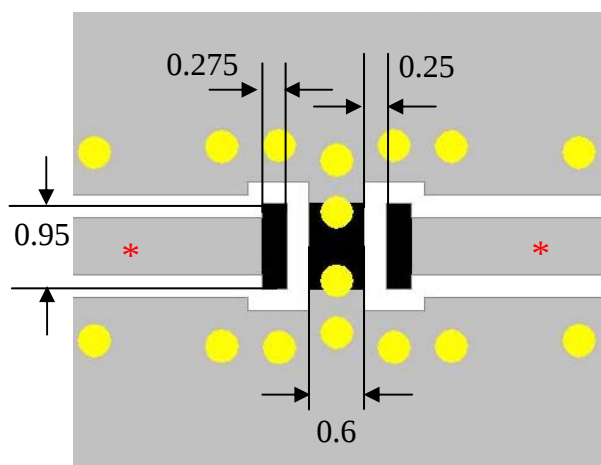


< Bottom View >



< Side View >

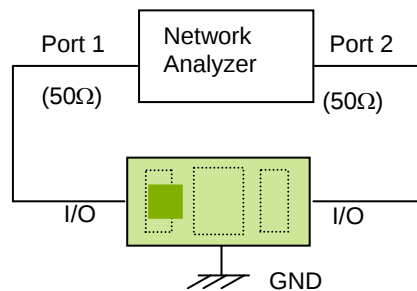
Mark	L	W	T	a	b	c	d
Dimensions	2.0 ± 0.15	1.25 ± 0.10	0.7 max.	0.95 ± 0.1	0.275 ± 0.1	0.6 ± 0.1	0.25 ± 0.05



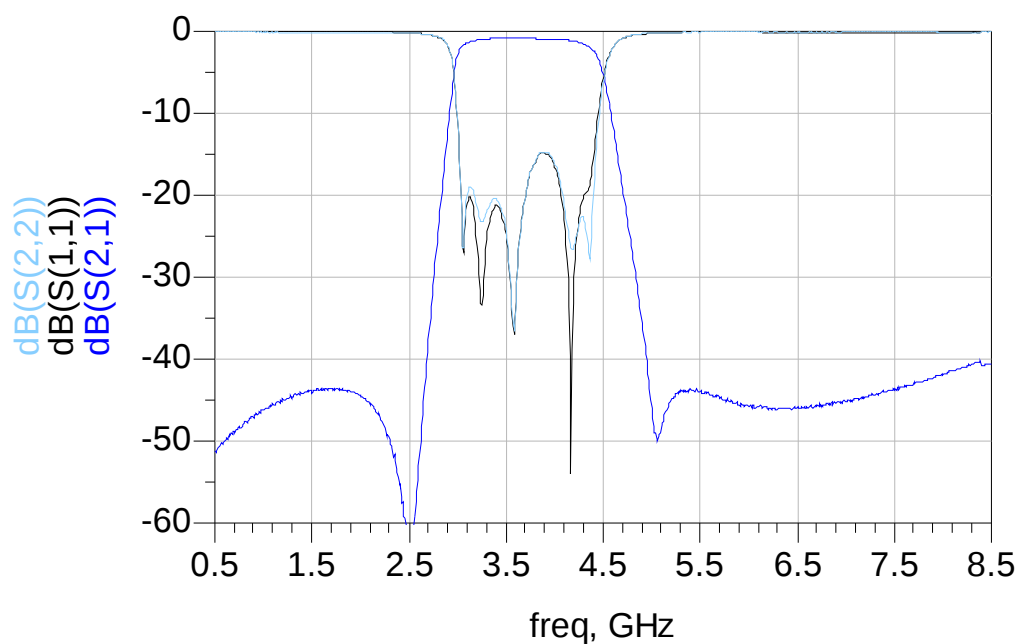
-  Solder Resist
-  Land
-  Through-hole ($\phi 0.35$)

* Line width should be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram



Electrical Characteristics (T=25°C)

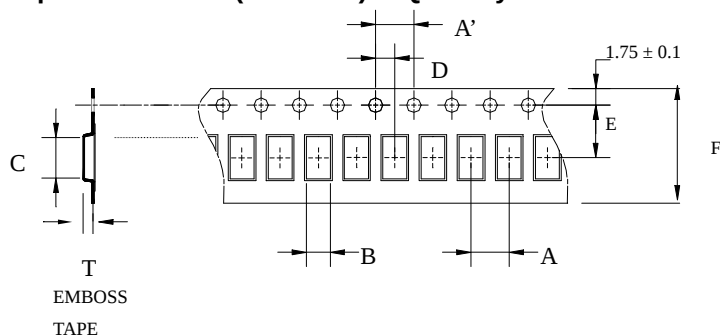


Notes

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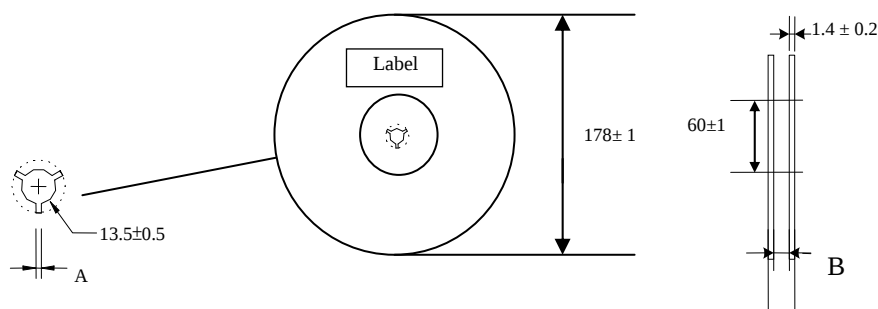
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
2012	4.0±0.1	4.0±0.1	1.35±0.05	2.15±0.05	2.0±0.05	3.5±0.1	8.0±0.1	0.65±0.05	4,000pcs	Plastic (Embossed)

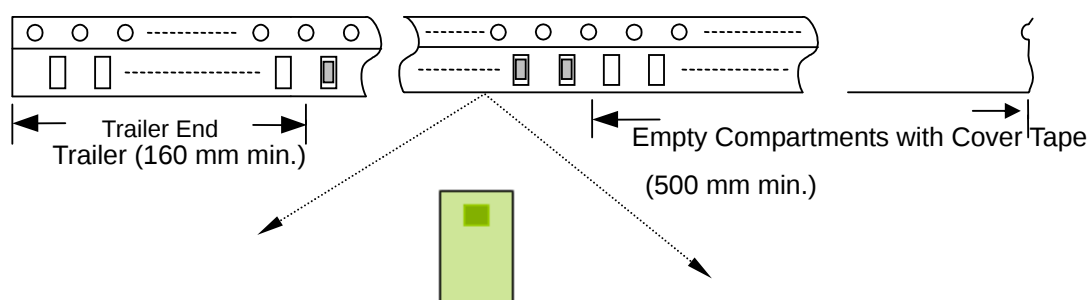
❖Reel Dimensions (Unit: mm)

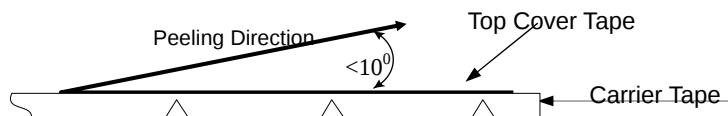


Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
2012	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape



❖ Peel-off Force

Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

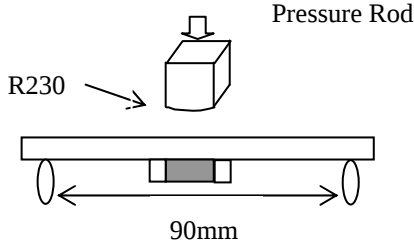
❖ Storage Conditions

- (1) Temperature: 5 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

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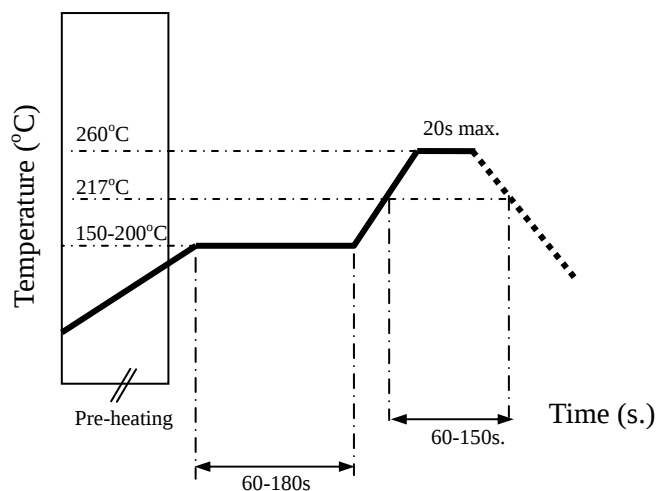
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	1. No apparent damage 2. More than 95% of the terminal electrode shall be covered with new solder	1. Preheat: $120 \pm 5^{\circ}\text{C}$ 2. Solder: $245 \pm 5^{\circ}\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	1. 10N minimum	1. Solder specimen onto test jig. 2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	1. No apparent damage	1. Solder specimen onto test jig (FR4, 1.6 mm) using the recommend soldering profile. 2. Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $85 \pm 2^{\circ}\text{C}$ 2. Humidity: 90% ~ 95% RH 3. Duration: 1000 ± 48hrs 4. Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	1. No apparent damage 2. Fulfill the electrical specification after test	1. One cycle/step 1 : $125 \pm 5^{\circ}\text{C}$ for 30 min step 2 : $-40 \pm 5^{\circ}\text{C}$ for 30 min 2. No of cycles : 100 3. Recovery: 1-2 hrs
Low Temperature Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $-40 \pm 5^{\circ}\text{C}$ 2. Duration: 500 ± 24hrs 3. Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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